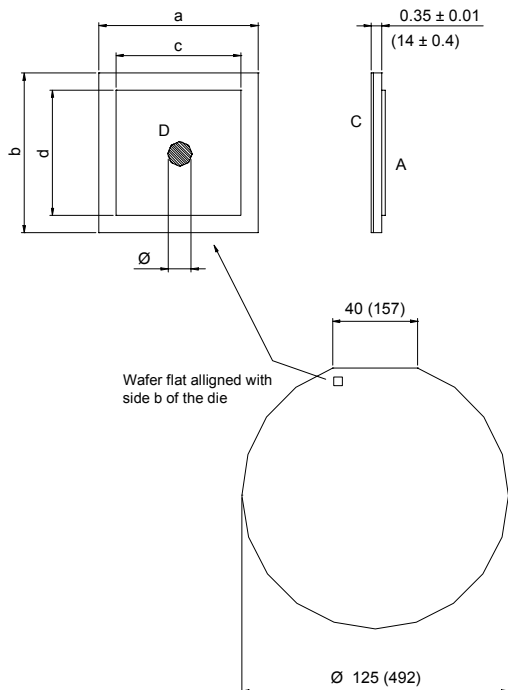


SCHOTTKY DIE 200 x 200 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).
2. CONTROLLING DIMENSION: (MILS).
3. DIMENSIONS AND TOLERANCES:
 - $a = 5.08 + 0, - 0.01$
(200 + 0, - 0.4)
 - $b = 5.08 + 0, - 0.01$
(200 + 0, - 0.4)
 - $c = 4.57 + 0, - 0.01$
(180 + 0, - 0.4)
 - $d = 4.57 + 0, - 0.01$
(180 + 0, - 0.4)
 - $\varnothing = 1 \pm 0.15$
(40 \pm 6)
4. LETTER DESIGNATION:
 - A = Anode (Top Metal)
 - C = Cathode (Back Metal)
 - D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
 - Recommended Blade
 - SEMITEC S1025 QS00 Blade
 - Sawing Street
 - 0.05 + 0, - 0.005
 - (2 + 0, - 0.2)

NOT TO SCALE

**NOTE: 10 mils die thickness is available on specific request only.
 Contact factory for information.**

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (µA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC200R015x5x	125	15	7500	900	0.45 @ 80A	D-61
SC200S020x5x	150	20	1200	450	0.51 @ 80A	D-61
SC200S030x5x	150	30	600	270	0.55 @ 80A	D-61
SC200S045x5x	150	45	400	210	0.66 @ 80A	D-61
SC200S060x5x	150	60	n.a. contact factory			
SC200H045x5x	175	45	70	26	0.74 @ 80A	D-61
SC200H100x5x	175	100	30	18	0.89 @ 60A	D-61
SC200H150x5x	175	150	15	10	1.14 @ 80A	D-61

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC200xxxxA5x	Wire Bondable	–	Al 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC200xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

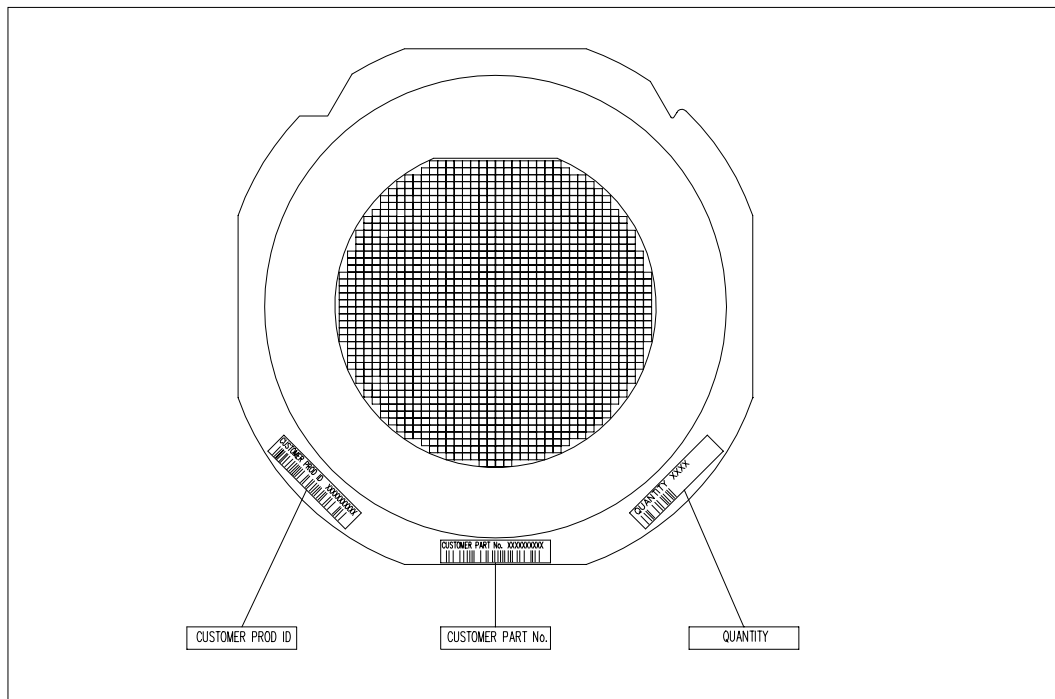
Device #	Description	Minimum Order Quantity Die in Sale Package
SC200xxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	350
SC200xxxx5R	Probed Die in Tape & Reel	8,000
SC200xxxx5P	Probed Die in Waffle Pack	350
SC200xxxx5F	Inked Probed Sawn Wafer on Film	350

Ordering Information Table

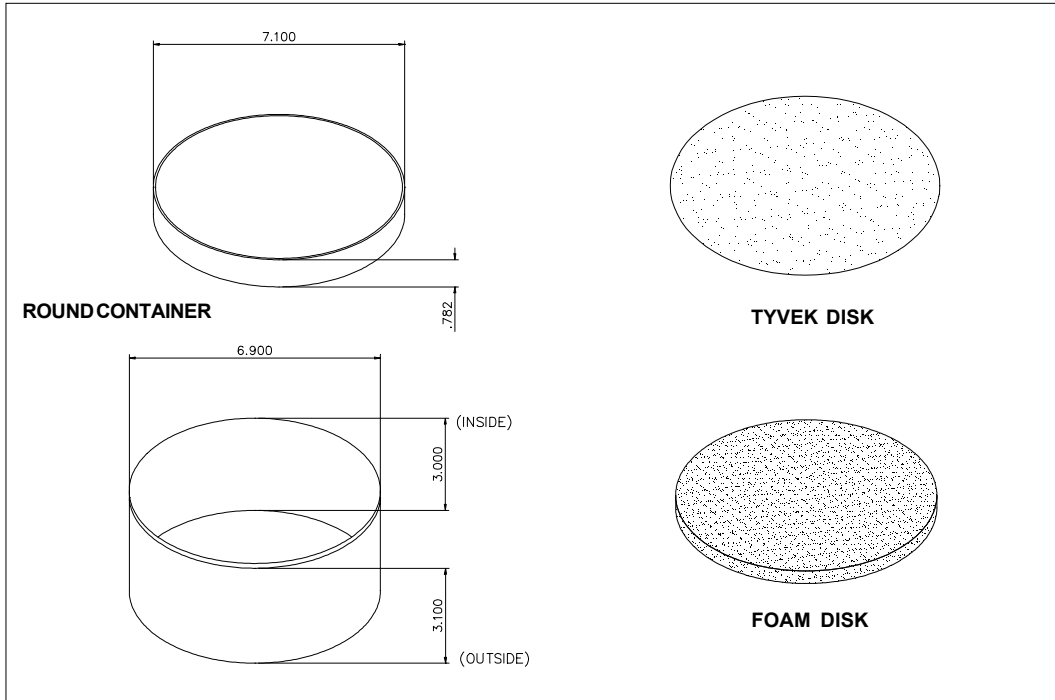
Device Code						
SC	200	S	100	A	5	B
①	②	③	④	⑤	⑥	⑦

<ul style="list-style-type: none"> 1 - Schottky Die 2 - Chip Dimension in Mils 3 - Process (see Electrical Characteristics Table) 4 - Voltage code: Code = V_{RRM} 5 - Chip surface metallization (see Mechanical Data Table) 6 - Wafer Diameter in inches 7 - Packaging (see Packaging Table) 	H = 830 Process R = OR'ing Process S = Standard Process
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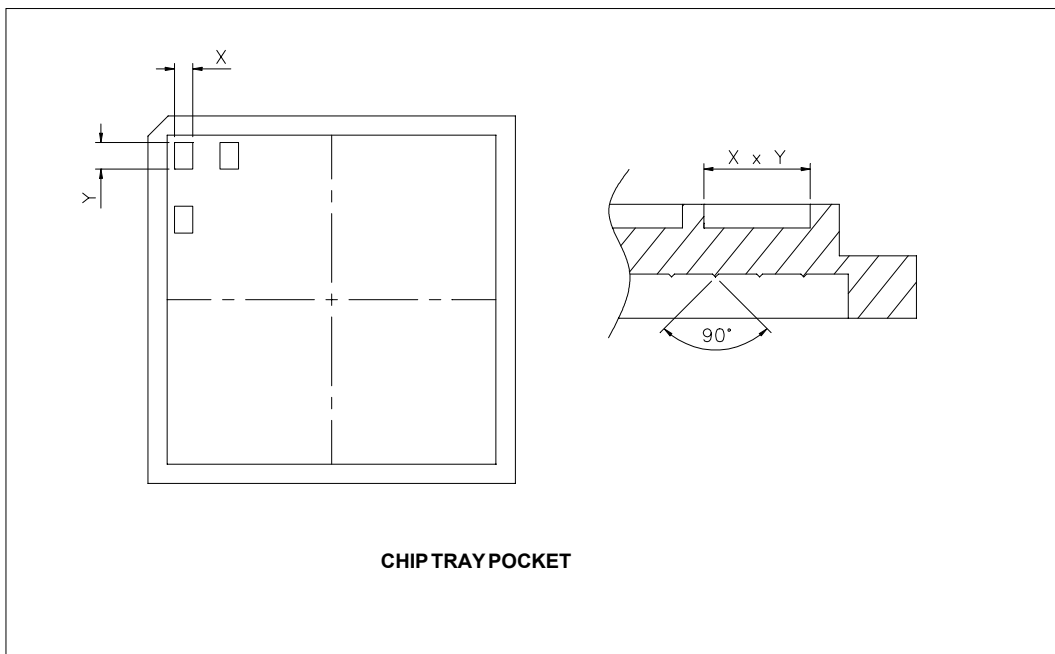
Wafer on Film



Wafer in Box



Die in Waffle Pack



Tape and Reel

